MEDIA FOR

THE 2001 ADVANCED PACKAGING AWARDS

And the Award Goes To...

At a special evening affair on July 18 at SEMICON West (San Jose), we learned for the first time the winners of the first annual awards program, launched by *Advanced Packaging* magazine and sponsored by SEMICON West

An unbiased and neutral panel of 10 judges from major universities, consortiums and consultancies used a 10-point scale to evaluate each entry based on the following seven factors: innovation; cost effectiveness; speed/throughput; quality; ease of use; maintainability; and environmental responsibility.

Congratulations to the winners of The 2001 Advanced Packaging Awards program, listed by category, company name and product entry.

Wafer Dicing

Covering sawing and other processes that separate chips in a wafer format

Lambda Physik USA Inc.
Gator

Die Placement and Attach

Including the handling, alignment and attachment of a chip to a substrate

Palomar Technologies
Laser Diode Attach Automated Assembly Cell

Wire Bonding

The time-honored process of making electrical connections from a chip to the next level of packaging with wire

Kulicke & Soffa Industries
Triton RDA (Ribbon Deep Access) Bonder

Interconnection

Covering the many methods of creating electrical contacts between components

Six Sigma
Column Attach Services

Encapsulation/Molding

The science and art of sealing a chip inside a more rugged housing

3M
No-Flow Underfill UF 3400

Solder Bumping

Covering the processes and equipment that create ball of bump interconnections on chips or packages
DEK
DirEKt Ball Placement System

Test & Inspection
Spanning the many processes and equipment used to evaluate products at all points in the process flow
Everett Charles Technologies
Automated Scanman

Contract Services
The critical business that lets companies hand off part of the process flow and focus on their own areas of expertise
ST Assembly Test Services Ltd. (STATS)
Simplified Package Modeling

Packing & Shipping/Distribution
The methods by which a customer actually receives a good part
RVSI
DT8000 High Performance Tape and Reel System

Software
For any part of the packaging process that is helped with specialized software
ESEC (USA) Inc.
B-BEM Adapter

Click here to see photos

Next year's program will be open to products launched from April 1, 2001 to March 31, 2002. To receive information about The 2002 Advanced Packaging Awards, please contact Amy Knutson-Strack.

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